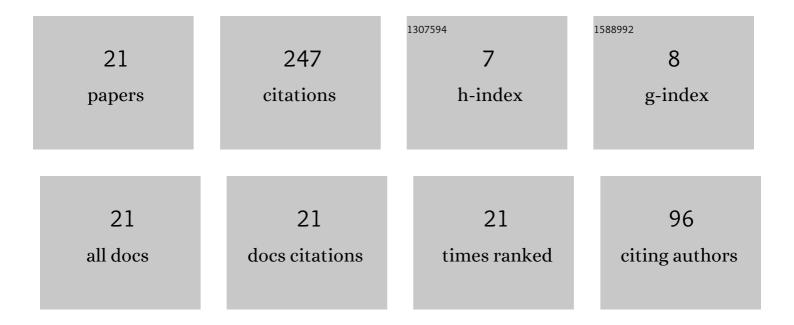
Yuling Niu

List of Publications by Year in descending order

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Υπηνς Νιπ

| # | Article | IF | CITATIONS |
|----|--|-----|-----------|
| 1 | A comprehensive solution for modeling moisture induced delamination in electronic packaging during solder reflow. Microelectronics Reliability, 2020, 112, 113791. | 1.7 | 18 |
| 2 | Design guideline on board-level thermomechanical reliability of 2.5D package. Microelectronics Reliability, 2020, 111, 113701. | 1.7 | 8 |
| 3 | Accessible determination of die-to-wafer bond strength with the Schwickerath test. Engineering Fracture Mechanics, 2020, 229, 106929. | 4.3 | 1 |
| 4 | Warpage Variation Analysis and Model Prediction for Molded Packages. , 2019, , . | | 3 |
| 5 | An Accurate Experimental Determination of Effective Strain for Heterogeneous Electronic Packages With Digital Image Correlation Method. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 678-688. | 2.5 | 10 |
| 6 | The Expermental and Numerical Study of Electromigration in 2.5D Packaging. , 2018, , . | | 14 |
| 7 | Design Guideline of 2.5D Package with Emphasis on Warpage Control and Thermal Management. , 2018, , | | 29 |
| 8 | Mechanical Strength Characterization of Direct Bond Interfaces for 3D-IC and MEMS Applications. , 2018, , . | | 2 |
| 9 | Experimentally Minimizing the Gap Distance Between Extra Tall Packages and PCB Using the Digital Image Correlation (DIC) Method. , 2018, , . | | 8 |
| 10 | Modeling and Design of 2.5D Package with Mitigated Warpage and Enhanced Thermo-Mechanical Reliability. , 2018, , . | | 17 |
| 11 | Comprehensive Study on 2.5D Package Design for Board-Level Reliability in Thermal Cycling and Power Cycling. , 2018, , . | | 31 |
| 12 | A comprehensive solution for electronic packages' reliability assessment with digital image correlation (DIC) method. Microelectronics Reliability, 2018, 87, 81-88. | 1.7 | 21 |
| 13 | A general strategy of in-situ warpage characterization for solder attached packages with digital image correlation method. Optics and Lasers in Engineering, 2017, 93, 9-18. | 3.8 | 13 |
| 14 | A Novel Speckle-Free Digital Image Correlation Method for In Situ Warpage Characterization. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, , 1-9. | 2.5 | 13 |
| 15 | An Investigation of Moisture-Induced Interfacial Delamination in Plastic IC Package During Solder Reflow. , 2017, , . | | 8 |
| 16 | A Study on the Thermomechanical Reliability Risks of Through-Silicon-Vias in Sensor Applications. Sensors, 2017, 17, 322. | 3.8 | 8 |
| 17 | The Complete Packaging Reliability Studies through One Digital Image Correlation System. , 2017, , . | | 10 |
| 18 | In-Situ Warpage Characterization of BGA Packages with Solder Balls Attached During Reflow with 3D Digital Image Correlation (DIC). , 2016, , . | | 14 |

| # | Article | IF | CITATIONS |
|----|---|----|-----------|
| 19 | Die stress in stealth dicing for MEMS. , 2016, , . | | 6 |
| 20 | A new in-situ warpage measurement of a wafer with speckle -free digital image correlation (DIC) method. , 2015, , . | | 11 |
| 21 | An Experimental and Numerical Study of the Dynamic Fracture of Glass. , 2013, , . | | 2 |